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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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1N4728A through 1N4753A

Silicon Epitaxial Planar Zener Diodes for Stabilized Power Supply

RENESAS

ADE-208-136C (Z)

Rev.3
Sep. 2000

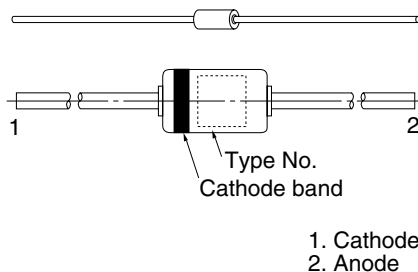
Features

- Glass package DO-41 structure ensures high reliability.
- Wide spectrum from 3.3V through 36V of zener voltage provide flexible application.

Ordering Information

Type No.	Mark	Package Code
1N4728A through 1N4753A	Type No.	DO-41

Pin Arrangement



Absolute Maximum Ratings

($T_a = 25^\circ\text{C}$)

Item	Symbol	Value	Unit
Power dissipation	P_d *1	1.0	W
Junction temperature	T_j	200	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 to +200	$^\circ\text{C}$

Note: 1. See Fig.3

1N4728A through 1N4753A

Electrical Characteristics

(Ta = 25°C)

Type No.	V_z (V) * ¹		I_R (μA)		Z_{ZT} (Ω)		Z_{ZK} (Ω)		I_{RSM} (mA)* ²
	Max	Test Condition	Max	Test Condition	Max	Test Condition	Max	Test Condition	Max
		I_z (mA)		V_R (V)		I_{ZT} (mA)		I_{ZK} (mA)	
1N4728A	3.3 ± 5 (%)	76	100	1.0	10	76	400	1.0	1380
1N4729A	3.6 ± 5 (%)	69	100	1.0	10	69	400	1.0	1260
1N4730A	3.9 ± 5 (%)	64	50	1.0	9	64	400	1.0	1190
1N4731A	4.3 ± 5 (%)	58	10	1.0	9	58	400	1.0	1070
1N4732A	4.7 ± 5 (%)	53	10	1.0	8	53	500	1.0	970
1N4733A	5.1 ± 5 (%)	49	10	1.0	7	49	550	1.0	890
1N4734A	5.6 ± 5 (%)	45	10	2.0	5	45	600	1.0	810
1N4735A	6.2 ± 5 (%)	41	10	3.0	2	41	700	1.0	730
1N4736A	6.8 ± 5 (%)	37	10	4.0	3.5	37	700	1.0	660
1N4737A	7.5 ± 5 (%)	34	10	5.0	4	34	700	0.5	605
1N4738A	8.2 ± 5 (%)	31	10	6.0	4.5	31	700	0.5	550
1N4739A	9.1 ± 5 (%)	28	10	7.0	5	28	700	0.5	500
1N4740A	10 ± 5 (%)	25	10	7.6	7	25	700	0.25	454
1N4741A	11 ± 5 (%)	23	5	8.4	8	23	700	0.25	414
1N4742A	12 ± 5 (%)	21	5	9.1	9	21	700	0.25	380
1N4743A	13 ± 5 (%)	19	5	9.9	10	19	700	0.25	344
1N4744A	15 ± 5 (%)	17	5	11.4	14	17	700	0.25	304
1N4745A	16 ± 5 (%)	15.5	5	12.2	16	15.5	750	0.25	285
1N4746A	18 ± 5 (%)	14.0	5	13.7	20	14.0	750	0.25	250
1N4747A	20 ± 5 (%)	12.5	5	15.2	22	12.5	750	0.25	225
1N4748A	22 ± 5 (%)	11.5	5	16.7	23	11.5	750	0.25	205
1N4749A	24 ± 5 (%)	10.5	5	18.2	25	10.5	750	0.25	190
1N4750A	27 ± 5 (%)	9.5	5	20.6	35	9.5	750	0.25	170
1N4751A	30 ± 5 (%)	8.5	5	22.8	40	8.5	1000	0.25	150
1N4752A	33 ± 5 (%)	7.5	5	25.1	45	7.5	1000	0.25	135
1N4753A	36 ± 5 (%)	7.0	5	27.4	50	7.0	1000	0.25	125

Notes: 1. Tested with DC

2. t = 1/120 sec reverse direction 1pulse

Main Characteristic

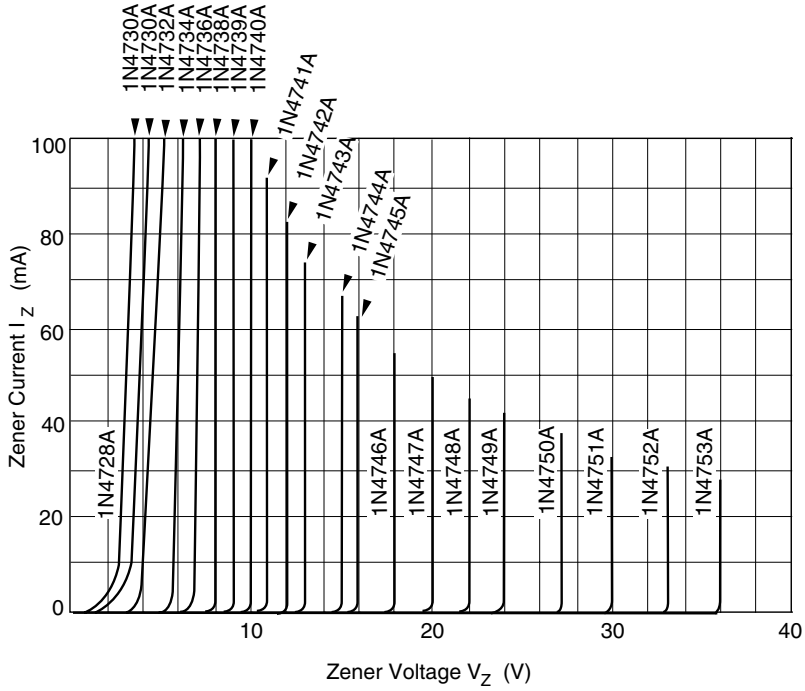


Fig.1 Zener current Vs. Zener voltage

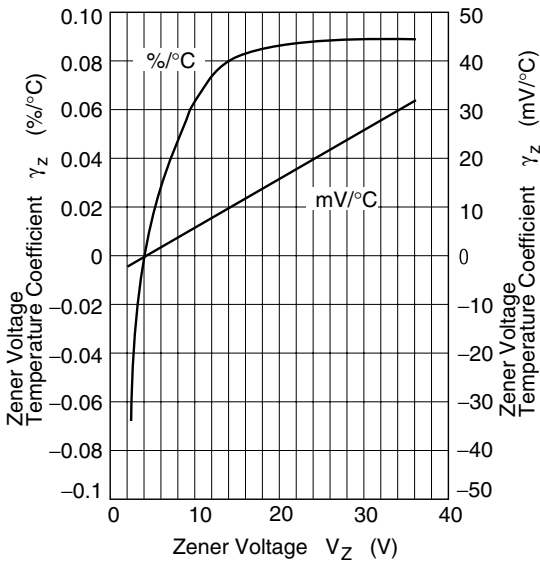


Fig.2 Temperature Coefficient Vs. Zener voltage

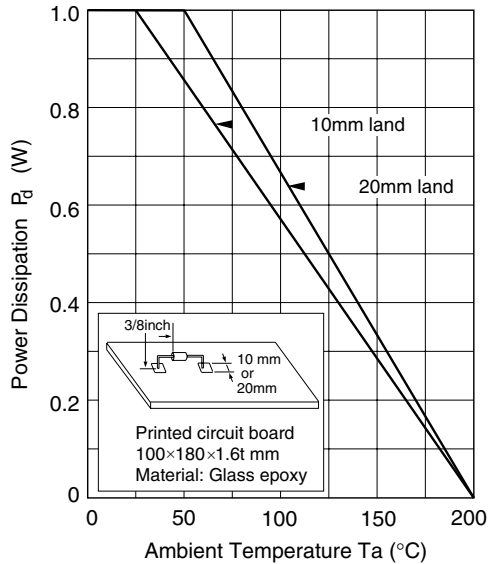


Fig.3 Power Dissipation Vs. Ambient Temperature

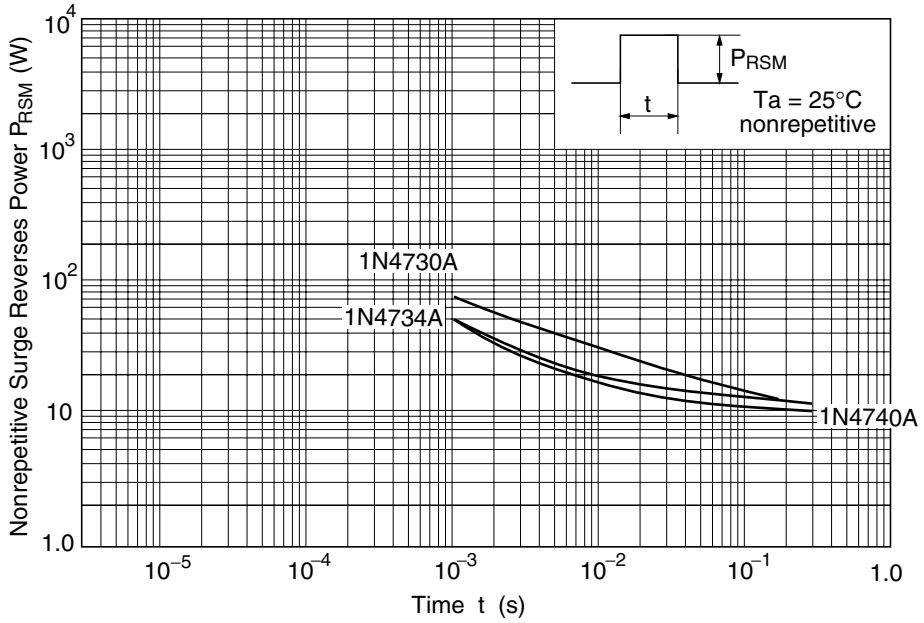


Fig.4 Surge Reverse Power Ratings

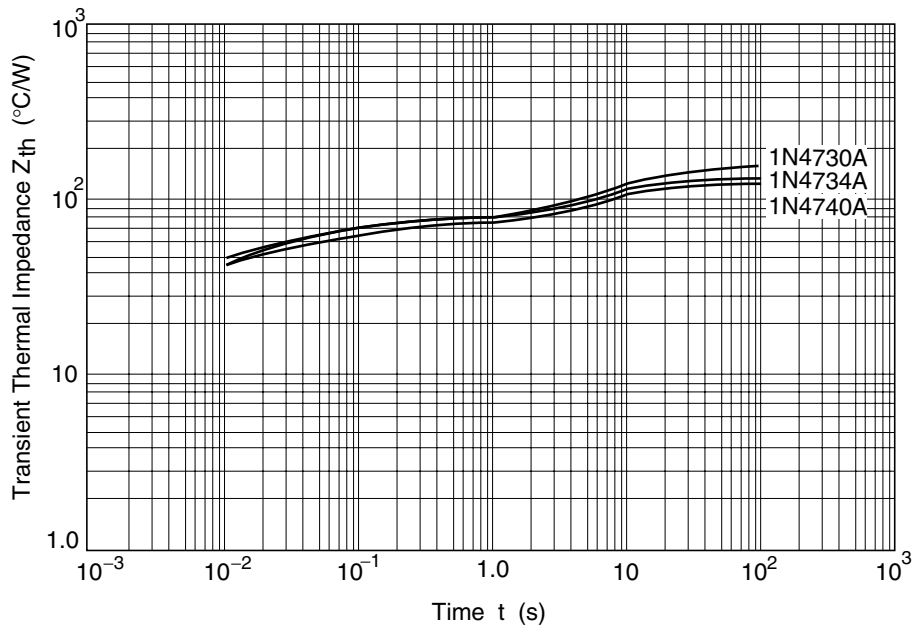
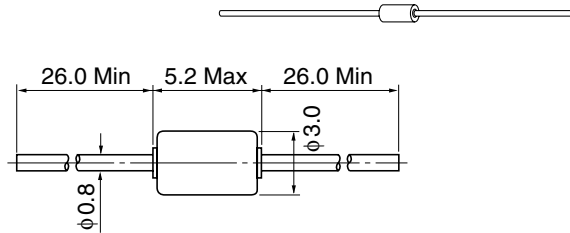


Fig.5 Transient Thermal Impedance

Package Dimensions

Unit: mm



Hitachi Code	DO-41
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.38 g

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Sales Offices

HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : <http://semiconductor.hitachi.com/>
 Europe : <http://www.hitachi-eu.com/hel/ecg>
 Asia : <http://sicapac.hitachi-asia.com>
 Japan : <http://www.hitachi.co.jp/Sicd/indx.htm>

For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe Ltd.
Electronic Components Group
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 585200

Hitachi Europe GmbH
Electronic Components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Asia Ltd.
Hitachi Tower
16 Collyer Quay #20-00
Singapore 049318
Tel: <65>-538-6533/538-8577
Fax : <65>-538-6933/538-3877
URL : <http://www.hitachi.com.sg>

Hitachi Asia Ltd.
(Taipei Branch Office)
4/F, No. 167, Tun Hwa North Road
Hung-Kuo Building
Taipei (105), Taiwan
Tel : <886>-(2)-2718-3666
Fax : <886>-(2)-2718-8180
Telex : 23222 HAS-TP
URL : <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon
Hong Kong
Tel : <852>-(2)-735-9218
Fax : <852>-(2)-730-0281
URL : <http://semiconductor.hitachi.com.hk>

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